



• General Description

It combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. It is suitable for automotive application.

• Features

- AEC-Q101 Qualified
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

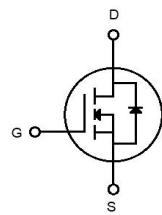
- BLDC Motor driver
- DC-DC
- Load Switch

• Ordering Information:

Part NO.	ZMSA055N15HB
Marking	ZMS055N15H
Packing Information	REEL TAPE
Basic ordering unit (pcs)	800

• Absolute Maximum Ratings ($T_c=25^\circ\text{C}$)

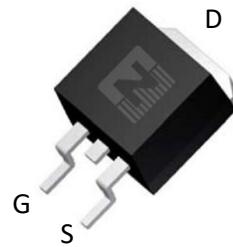
Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		150	V
Gate-Source Voltage ^①	V_{GS}		± 20	V
Continuous Drain Current	I_D	$T_c=25^\circ\text{C}$	109	A
	I_D	$T_c=75^\circ\text{C}$	89	A
	I_D	$T_c=100^\circ\text{C}$	77	A
Pulsed Drain Current	I_{DM}	Pulsed; $t_p \leq 10 \mu\text{s}$; $T_{mb} = 25^\circ\text{C}$	436	A
Total Power Dissipation	P_D	$T_c=25^\circ\text{C}$	214	W
Total Power Dissipation	P_D	$T_A=25^\circ\text{C}$	3.8	W
Operating Junction Temperature	T_J		-55 to +175	$^\circ\text{C}$
Storage Temperature	T_{STG}		-55 to +175	$^\circ\text{C}$
Single Pulse Avalanche Energy	E_{AS}	$L=0.1\text{mH}$, $V_{GS}=10\text{V}$, $R_g=25\Omega$,	390	mJ
		$L=0.5\text{mH}$, $V_{GS}=10\text{V}$, $R_g=25\Omega$,	702	mJ
ESD Level (HBM)			CLASS 2	



$V_{DS}=150\text{V}$

$R_{DS(ON)}=6.5\text{m}\Omega$

$I_D=109\text{A}$



TO-263



HF



•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}		-	0.7	°C/W
Thermal resistance, junction-ambient	R _{thJA} ⁽²⁾		-	40	°C/W
Soldering temperature (total time<10s)	T _{sold}		-	260	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	150			V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} =V _{DS} , I _D =250uA	2.0	3.3	4.0	V
Drain-Source Leakage Current	I _{DSS}	V _{GS} =0V, V _{DS} = 150V			1.0	uA
Gate- Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} = 0V			100	nA
Static Drain-source On Resistance	R _{DS(ON)}	V _{GS} =10V, I _D = 30A		6.5	8.5	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V, I _{SD} = 20A		45		s
Diode Forward Voltage	V _{FSD}	V _{GS} =0V, I _{SD} = 30A			1.3	V

•Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C _{iss}	f = 1MHz, V _{DS} =25V	-	6600	-	pF
Output capacitance	C _{oss}		-	2750	-	
Reverse transfer capacitance	C _{rss}		-	256	-	
Gate Resistance	R _g	f = 1MHz	-	1.2		Ω
Total gate charge	Q _g	V _{DD} = 15V, I _D = 20A, V _{GS} = 10V	-	98	-	nC
Gate - Source charge	Q _{gs}		-	28	-	
Gate - Drain charge	Q _{gd}		-	25	-	
Turn-ON Delay time	t _{D(on)}	V _{GS} =10V,V _{DS} =15V, R _G =3.3Ω, I _D =20A	-	30	-	ns
Turn-ON Rise time	t _r		-	12	-	ns
Turn-Off Delay time	t _{D(off)}		-	65	-	ns
Turn-Off Fall time	t _f		-	14	-	ns
Reverse Recovery Time	t _{RR}	V _{DD} =20V, dI _S /dt = 100A/s, I _S =50A	-	72	-	ns
Reverse Recovery Charge	Q _{RR}		-	98	-	nC



Fig.1 Gate-Charge Characteristics

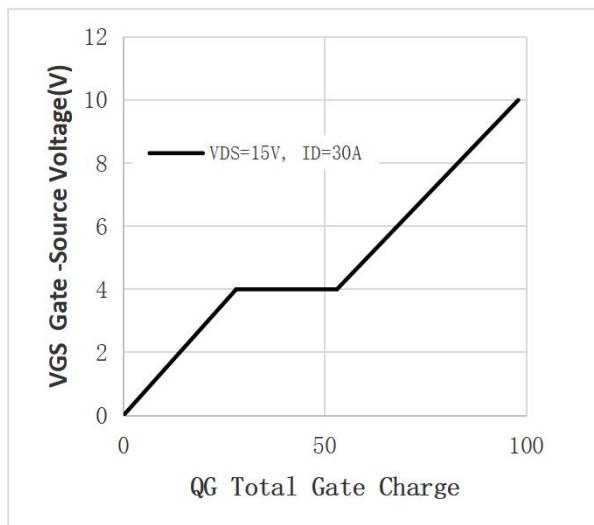


Fig.2 Capacitance Characteristics

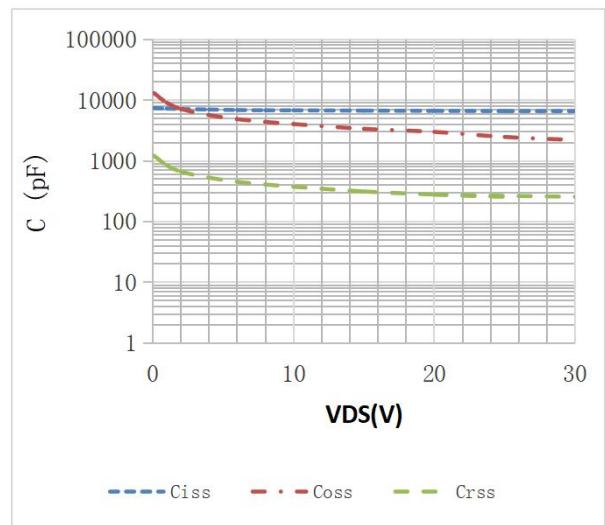


Fig.3 Power Dissipation

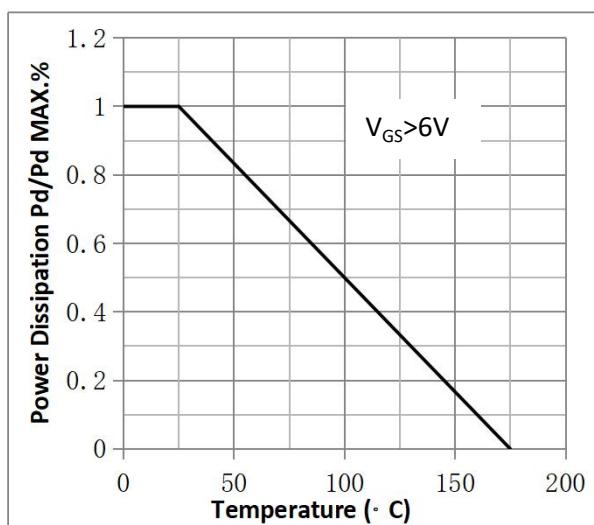


Fig.4 Typical output Characteristics

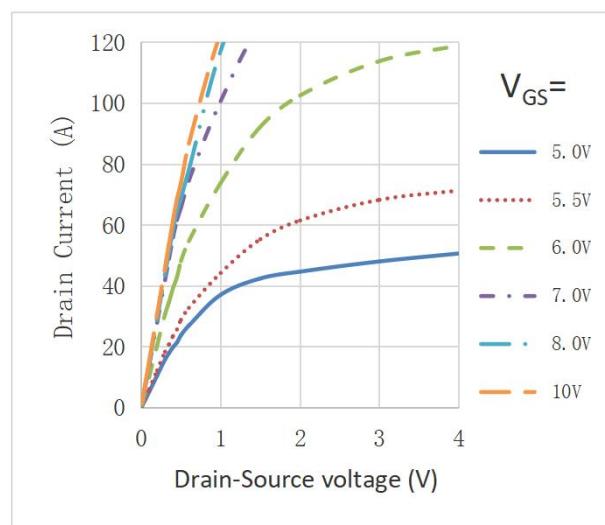


Fig.5 Threshold Voltage V.S Junction Temperature

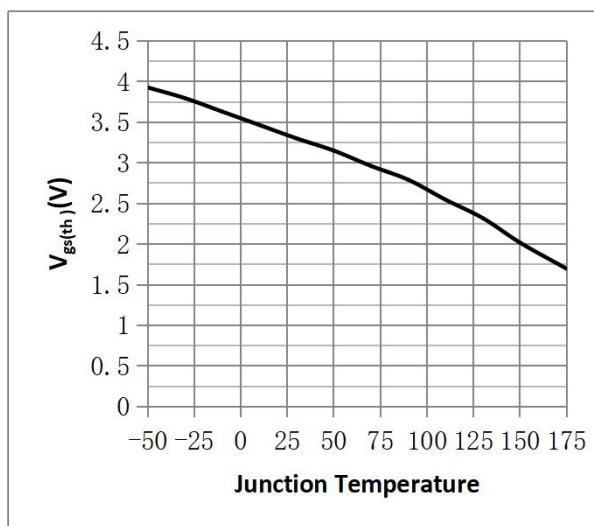


Fig.6 Resistance V.S Drain Current

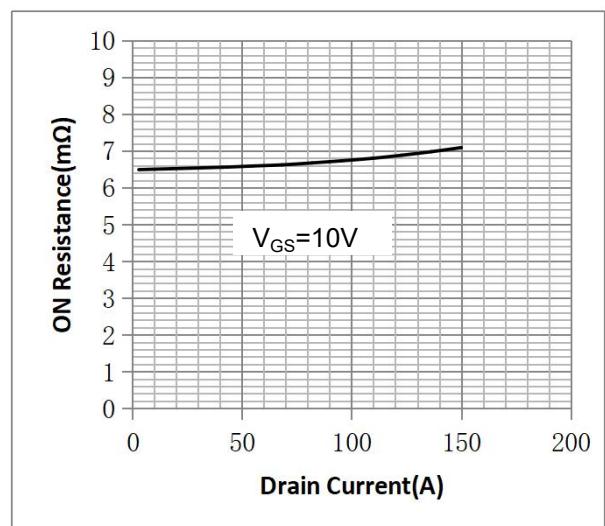




Fig.7 On-Resistance VS Gate Source Voltage

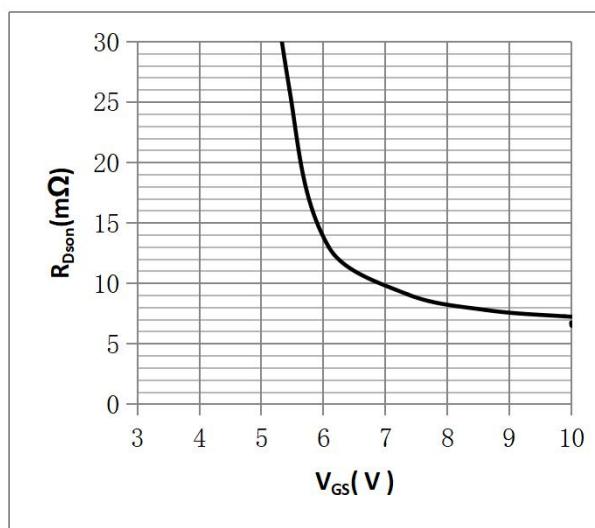


Figure 9. Diode Forward Voltage vs. Current

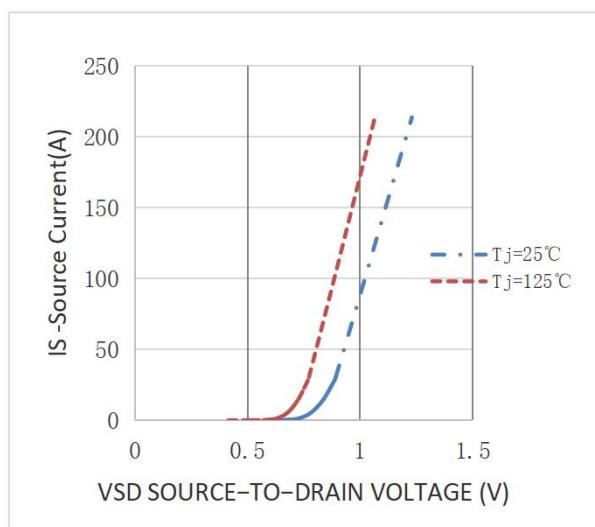


Fig.11 SOA Maximum Safe Operating Area

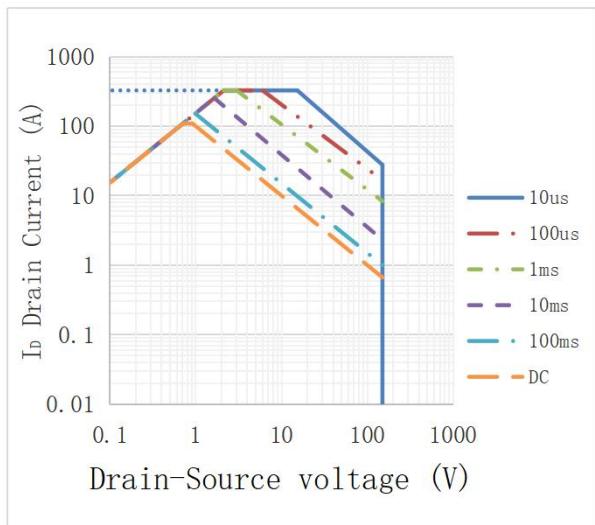


Fig.8 On-Resistance V.S Junction Temperature

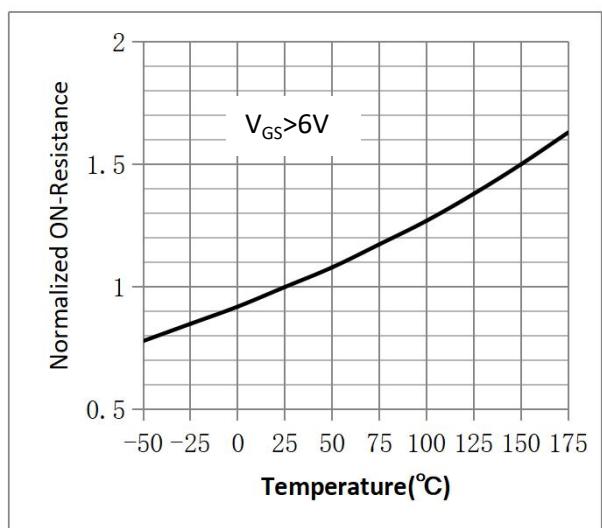
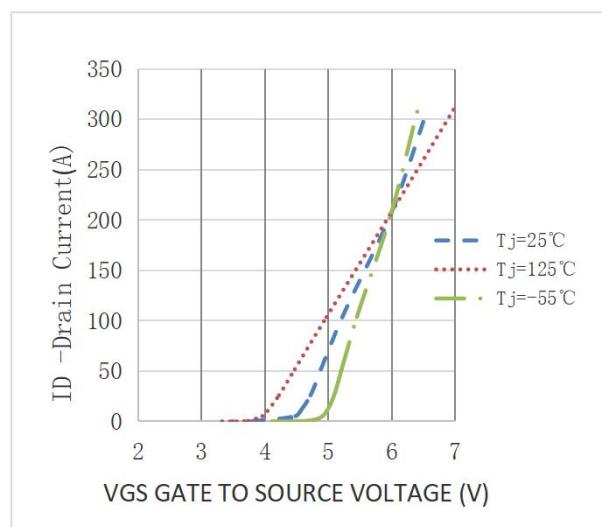
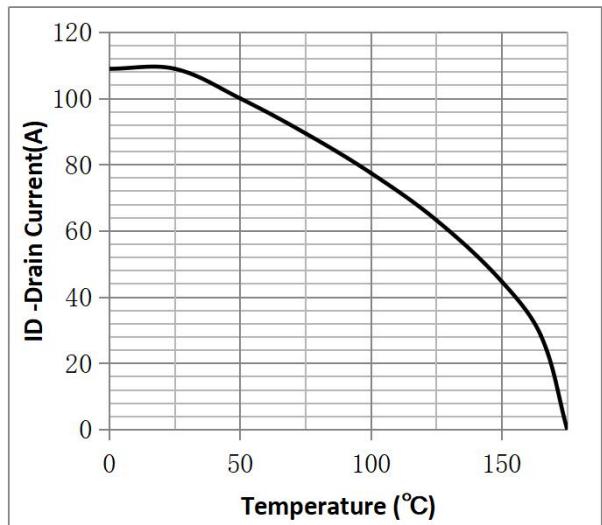
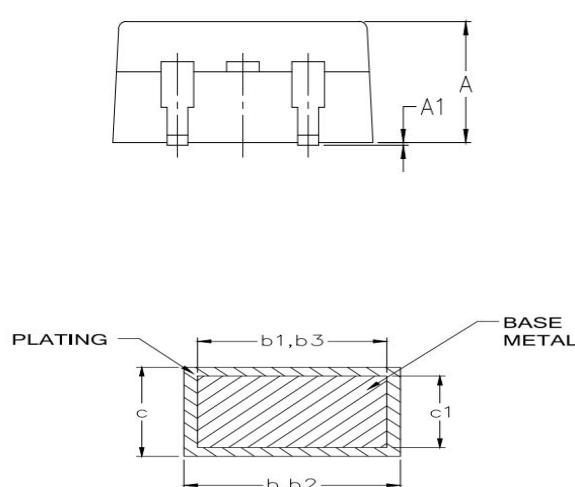
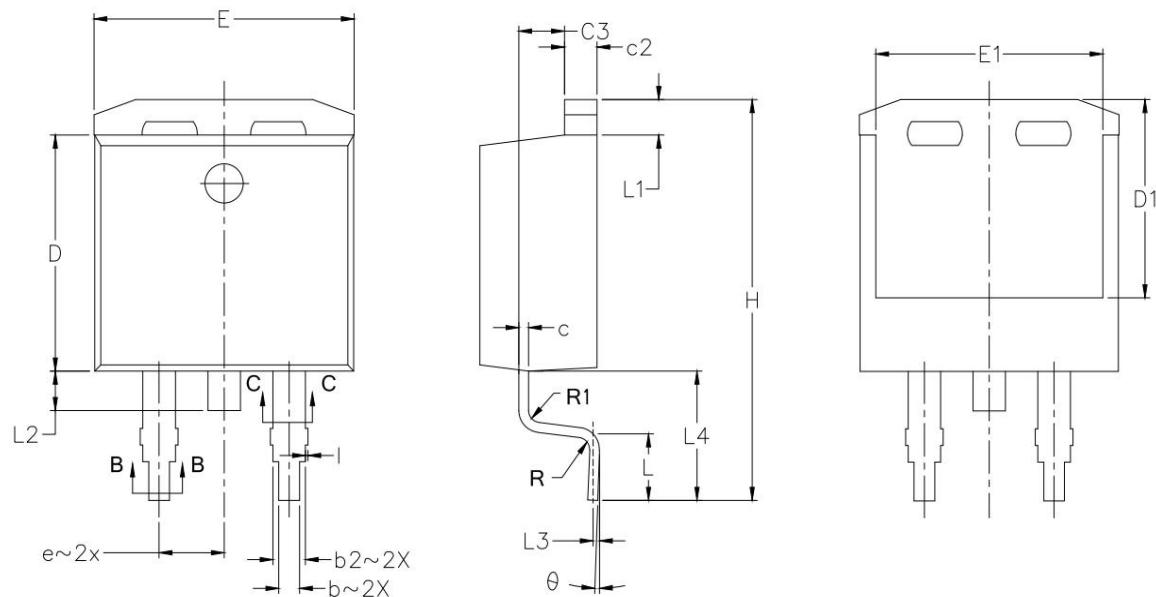


Figure 10. Transfer Characteristics

Fig.12 ID vs. Junction Temperature^③



•TO-263 Package Outline



SYMBOLS	COMMON			
	MM		INCH	
	MIN.	MAX.	MIN.	MAX.
A	4.064	4.826	0.160	0.190
A1	0.000	0.254	0.000	0.010
b	0.508	0.991	0.020	0.039
b1	0.508	0.889	0.020	0.035
b2	1.143	1.778	0.045	0.070
b3	1.143	1.727	0.045	0.068
c	0.381	0.737	0.015	0.029
c1	0.381	0.584	0.015	0.023
c2	1.143	1.651	0.045	0.065
D	8.382	9.652	0.330	0.380
D1	6.858	—	0.270	—
E	9.652	10.668	0.380	0.420
E1	6.223	—	0.245	—
e	2.540 BSC.	—	0.100 BSC.	—
H	14.605	15.875	0.575	0.625
L	1.778	2.794	0.070	0.110
L1	—	1.676	—	0.066
L2	—	1.778	—	0.070
L3	0.254 BSC	—	0.010 BSC	—
L4	4.780	5.280	0.188	0.208
R	0.460 TYP	—	0.018 TYP	—
R1	0.460 TYP	—	0.018 TYP	—
θ	0°	8°	0°	8°
C3	1.68	1.88	0.0661	0.0740
I	-	0.100	-	0.0039

**Note:**

- ① Pulse : VGS=+20V/-20V, Duty cycle=50%, Tj=175°C, t=1000 hours; For DC , the following test conditions can be passed: VGS=+20V/-10V, Tj=175°C, t=1000 hours;
- ② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ③ Practically the current will be limited by PCB, thermal design and operating temperature. V_{GS}=10V.

Disclaimer

- Reproducing and modifying information of the document is prohibited without permission from ZMJ SEMICONDUCTORS CO.,LTD.
- ZMJ SEMICONDUCTORS CO.,LTD. reserves the rights to make changes of the content herein the document anytime without notification. Please refer to our website for the latest document.
- ZMJ SEMICONDUCTORS CO.,LTD. disclaims any and all liability arising out of the application or use of any product including damages incidentally and consequentially occurred.
- ZMJ SEMICONDUCTORS CO.,LTD. does not assume any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.
- Applications shown on the herein document are examples of standard use and operation. Customers are responsible in comprehending the suitable use in particular applications. ZMJ SEMICONDUCTORS CO.,LTD. makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.
- The products shown herein are not designed and authorized for equipments relating to human life and for any applications concerning life-saving or life-sustaining, such as medical instruments, aerospace machinery et cetera. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify ZMJ SEMICONDUCTORS CO.,LTD. for any damages resulting from such improper use or sale.
- Since ZMJ uses lot number as the tracking base, please provide the lot number for tracking when complaining.



Revision History

Version	Date	Change
A	2022.4.6	New
B	2022.10.21	1.Fig.1~Fig11 modify 2.Idm corrected 3.Add Reach,HF figure 4.add "It is